Dual 2-Bit Dual-Supply Non-Inverting Level Translator

The NLSV22T244 is a dual 2-bit configurable dual-supply bus buffer level translator. The input ports A and the output ports B are designed to track two different power supply rails V_{CCA} and V_{CCB} . Both supply rails are configurable from 1.6 V to 3.6 V allowing universal low-voltage translations from the input port A to the output B port.

Features

- Wide V_{CCA} and V_{CCB} Operating Range: 1.6 V to 3.6 V
- High-Speed w/ Balanced Propagation Delay
- Inputs and Outputs have OVT Protection to 5.5 V
- Non-preferential V_{CCA} and V_{CCB} Sequencing
- Outputs at 3-State until Active V_{CC} is reached
- Power-Off Protection
- Ultra-Small packaging: 1.7mm x 2.0 mm UQFN-12
- This is a Pb-Free Device

Typical Applications

• Mobile Phones, PDAs, Other Portable Devices

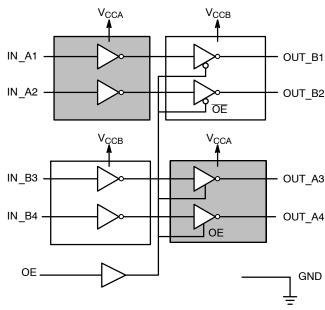


Figure 1. Logic Diagram



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MARKING DIAGRAM

WEM■

UQFN12 MU SUFFIX CASE 523AE

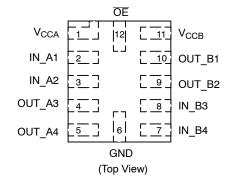
WE = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

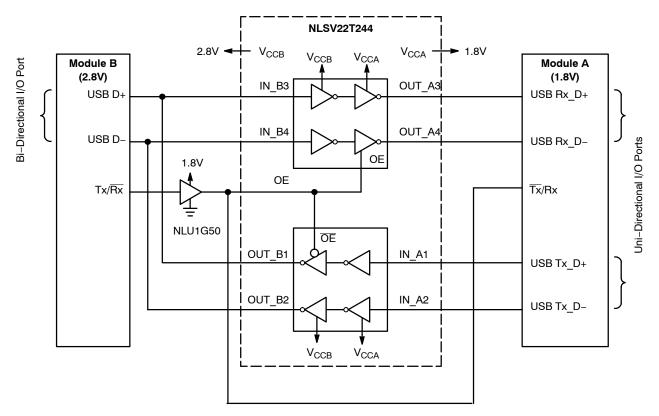
PIN ASSIGNMENT



ORDERING INFORMATION

Device	Package	Shipping [†]
NLSV22T244MUTAG	UQFN12 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.



 $\mathsf{OE} = \mathsf{High}, \, \mathsf{Module} \, \mathsf{B} \, \mathsf{Transmits}, \, \mathsf{Module} \, \mathsf{A} \, \mathsf{Receives} = \mathsf{B} \to \mathsf{A}$

OE = Low, Module A Transmits, Module B Receives = $\mathbf{A} \to \mathbf{B}$

Figure 2. Typical Application Bi-Directional to Uni-Directional Logic Level Translator

PIN ASSIGNMENT

Pin	Function
V _{CCA}	A DC Power Supply
V _{CCB}	B DC Power Supply
GND	Ground
IN_A1, IN_A2, IN_B3, IN_B4	Inputs
OUT_B1, OUT_B2, OUT_A3, OUT_A4	Outputs
OE	Output Enable

In	puts	Outputs		
OE	IN_A1 IN_A2	IN_B3, IN_B4	OUT_B1, OUT_B2	OUT_A3 OUT_A4
Н	Х	L	3-State	L
	L	Н		Н
L	L	Х	L	3-State
	Н		Н	

MAXIMUM RATINGS

Symbol	Rating	Value	Condition	Unit
V _{CCA} , V _{CCB}	DC Supply Voltage	-0.5 to +5.5		V
VI	DC Input Voltage IN_X _n	-0.5 to +5.5		V
V _C	Control Input OE	-0.5 to +5.5		V
Vo	DC Output Voltage (Power Down) OUT_X _n	-0.5 to +5.5	V _{CCA} = V _{CCB} = 0	V
	(Active Mode) OUT_X _n	-0.5 to +5.5		
	(Tri-State Mode) OUT_X _n	-0.5 to +5.5		
l _{IK}	DC Input Diode Current	-20	V _I < GND	mA
lok	DC Output Diode Current	-50	V _O < GND	mA
I _O	DC Output Source/Sink Current	±50		mA
I _{CCA} , I _{CCB}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current per Ground Pin	±100		mA
T _{STG}	Storage Temperature	-65 to +150		°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CCA} , V _{CCB}	Positive DC Supply Voltage	1.6	3.6	V
VI	Bus Input Voltage	GND	3.6	V
V _C	Control Input OE	GND	3.6	V
V _{IO}	Bus Output Voltage (Power Down Mode) OUT_X _n	GND	3.6	V
	(Active Mode) OUT_X _n	GND	3.6	V
	(Tri-State Mode) OUT_X _n	GND	3.6	V
T _A	Operating Temperature Range	-40	+85	°C
Δt / ΔV	Input Transition Rise or Rate V_{l} , from 30% to 70% of V_{CC} ; V_{CC} = 3.3 V ±0.3 V	0	10	nS

DC ELECTRICAL CHARACTERISTICS

					-40°C t	o +85°C	
Symbol	Parameter	Test Conditions	V _{CCA} (V)	V _{CCB} (V)	Min	Max	Unit
V _{IH}	Input HIGH Voltage		2.7 – 3.6	1.6 – 3.6	2.0	_	V
			2.3 – 2.7	1	1.6	-	
			1.4 – 2.3	1	0.65 * V _{CCA}	_	
V_{IL}	Input LOW Voltage		2.7 – 3.6	1.6 – 3.6	-	0.8	V
			2.3 – 2.7	1	-	0.7	
			1.6 – 2.3	1	-	0.35 * V _{CCA}	
V _{OH}	Output HIGH Voltage	$I_{OH} = -100 \mu A; V_I = V_{IH}$	1.6 – 3.6	1.6 – 3.6	V _{CCB} - 0.2	_	V
		$I_{OH} = -6 \text{ mA}; V_I = V_{IH}$	1.6	1.6	1.25	_	
			2.3	2.3	2.0	_	
		$I_{OH} = -12 \text{ mA}; V_I = V_{IH}$	2.3	2.3	1.8	_	
			2.7	2.7	2.2	_	
		$I_{OH} = -18 \text{ mA}; V_I = V_{IH}$	2.3	2.3	1.7	-	
			3.0	3.0	2.4	_	
		$I_{OH} = -24 \text{ mA}; V_I = V_{IH}$	3.0	3.0	2.2	_	
V _{OL}	Output LOW Voltage	$I_{OL} = 100 \mu A; V_I = V_{IL}$	1.6 – 3.6	1.6 – 3.6	-	0.2	V
		$I_{OL} = 6 \text{ mA}; V_I = V_{IL}$	1.6	1.6	-	0.3	
		I_{OL} = 12 mA; V_I = V_{IL}	2.3	2.3	-	0.4	
			2.7	2.7	-	0.4	
		I_{OL} = 18 mA; $V_I = V_{IL}$	2.3	2.3	-	0.6	
			3.0	3.0	-	0.5	
		I_{OL} = 24 mA; V_I = V_{IL}	3.0	3.0	-	0.6	
I _I	Input Leakage Current	V _I = V _{CCA} or GND	1.6 – 3.6	1.6 – 3.6	-1.0	+1.0	μΑ
I _{OZ}	I/O Tri-State Output Leakage Current	$T_A = 25^{\circ}C$, OE = GND	1.6 – 3.6	1.6 – 3.6	_	2.0	μΑ
I _{CCA}	Quiescent Supply Current	$V_I = V_{CCA}$ or GND; $I_O = 0$	1.6 – 3.6	1.6 – 3.6	-	2.0	μΑ
I _{CCB}	Quiescent Supply Current	$V_I = V_{CCA}$ or GND; $I_O = 0$	1.6 – 3.6	1.6 – 3.6	_	2.0	μΑ
I _{CCA} + I _{CCB}	Quiescent Supply Current	$V_I = V_{CCA}$ or GND; $I_O = 0$	1.6 – 3.6	1.6 – 3.6	-	4.0	μΑ

TOTAL STATIC POWER CONSUMPTION (I_{CCA} + I_{CCB})

		(OCA O	, OD,				
			-40°C	to +85°C			
	V _{CCB} (V)						
	3	3.6	2	2.8	1	.6	
V _{CCA} (V)	Min	Max	Min	Max	Min	Max	Unit
3.6		2		2		2	μΑ
2.8		< 1		< 1		< 0.5	μΑ
1.6		< 1		< 1		< 0.5	μΑ

NOTE: Connect ground before applying supply voltage V_{CCA} or V_{CCB} . This device is designed with the feature that the power-up sequence of V_{CCA} and V_{CCB} will not damage the IC.

AC ELECTRICAL CHARACTERISTICS

					-40°C 1	to +85°C			
					Vcc	_B (V)			
			3	3.6	2	2.8	1	.6	
Symbol	Parameter	V _{CCA} (V)	Min	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Propagation Delay,	3.6		3.4		3.6		3.8	nS
t _{PHL}	A _n to B _n	2.8		3.6		3.8		4.0	
		1.6		3.9		4.0		4.5	
t _{PZH} ,	Output Enable, OE to OUT_X _n	3.6		5.8		6.0		6.2	nS
t_{PZL}		2.8		6.0		6.2		6.4	
		1.6		8.2		8.4		8.6	
t _{PHZ} ,	Output Disable,	3.6		5.8		6.0		6.2	nS
t_{PLZ}	OE to OUT_X _n	2.8		6.0		6.2		6.4	
		1.6		8.2		8.4		8.6	
t _{OSHL} ,	Output-to-Output Skew, Data-to-Output	3.6		0.15		0.15		0.15	nS
toslh		2.8		0.15		0.15		0.15	
		1.6		0.15		0.15		0.15	

^{1.} Propagation delays defined per Figure 3.

CAPACITANCE

Symbol	Parameter	Test Conditions	Typ (Note 2)	Unit
C _{IN}	Control Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CCA/B}$	3.5	pF
C _{I/O}	I/O Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CCA/B}$	5.0	pF
C _{PD}	Power Dissipation Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CCA}, f = 10 \text{ MHz}$	10	pF

Typical values are at T_A = +25°C.
 C_{PD} is defined as the value of the IC's equivalent capacitance from which the operating current can be calculated from: $I_{CC(\text{operating})} \cong C_{PD} \times V_{CC} \times f_{IN} \times N_{SW}$ where $I_{CC} = I_{CCA} + I_{CCB}$ and $N_{SW} = \text{total number of outputs switching}$.

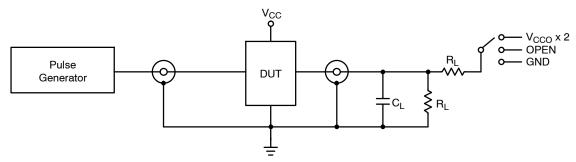


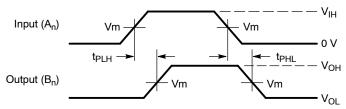
Figure 3. AC (Propagation Delay) Test Circuit

Test	Switch
t _{PLH} , t _{PHL}	OPEN
t _{PLZ} , t _{PZL}	V _{CCO} x 2 at VCCB = 3.0 V - 3.6 mV, 2.3 V - 2.7 V, 1.6 V - 1.95 V
t _{PHZ} , t _{PZH}	GND

C_L = 15 pF or equivalent (includes probe and jig capacitance)

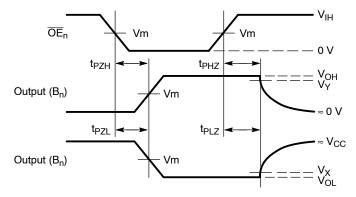
 R_L = 2 $k\Omega$ or equivalent

 Z_{OUT} of pulse generator = 50 Ω



Waveform 1 - Propagation Delays

 $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$



Waveform 2 - Output Enable and Disable Times

 $t_R = t_F = 2.0 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

Figure 4. AC (Propagation Delay) Test Circuit Waveforms

	V _{CC}
Symbol	3.0 V – 3.6 V
V _{mA}	V _{CCA} /2
V_{mB}	V _{CCB} /2
V _X	V _{OL} x 0.1
V _Y	V _{OH} x 0.9

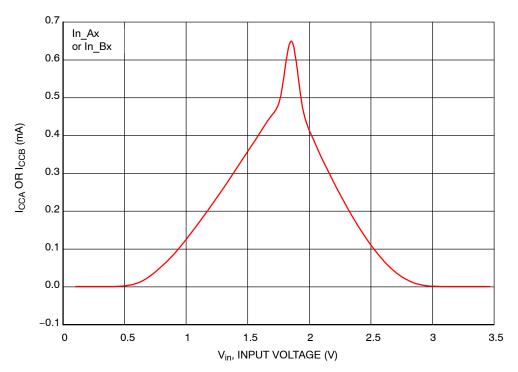


Figure 5. Delta I_{CC} Increase in I_{CC} per Input Voltage, Other Inputs at $V_{CCA}\,/\,V_{CCB}$ or GND

UQFN12 1.7x2.0, 0.4P CASE 523AE-01 **ISSUE A**



DATE 11 JUN 2007



PIN 1 REFERENCE

2X |

12X 🗀

0.10 C

0.10 C

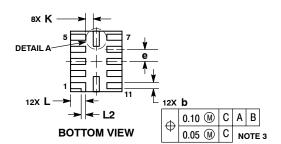




CONSTRUCTION

0.05 С 0.05 C **A1** SEATING PLANE SIDE VIEW

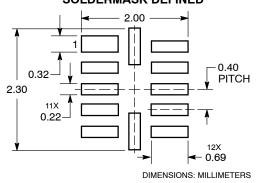
TOP VIEW



DETAIL B

-A B

MOUNTING FOOTPRINT SOLDERMASK DEFINED



NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM
- FROM TERMINAL TIP.

 MOLD FLASH ALLOWED ON TERMINALS

 ALONG EDGE OF PACKAGE. FLASH 0.03

 MAX ON BOTTOM SURFACE OF
- TERMINALS.
 DETAIL A SHOWS OPTIONAL
 CONSTRUCTION FOR TERMINALS.

	MILLIMETERS				
DIM	MIN	MAX			
Α	0.45	0.55			
A1	0.00	0.05			
A3	0.127 REF				
b	0.15	0.25			
D	1.70	BSC			
Е	2.00	BSC			
е	0.40	BSC			
K	0.20				
L	0.45	0.55			
L1	0.00	0.03			
12	0.15	REF			

GENERIC MARKING DIAGRAM*



XX = Specific Device Code

= Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

DOCUMENT NUMBER:	98AON23418D	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED	
DESCRIPTION:	UQFN12 1.7 X 2.0, 0.4P		PAGE 1 OF 1

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